

Product Information Sheet

MATERIAL ID:	EPO-TEK® EV2002 (formerly EE162-5)
Date: 04/2006	Per:
Rev: 1	
Material Description:	Silver-filled, electrically conductive, flexible epoxy
Number of Components:	Two
Mix Ratio by weight:	4:1
Cure Schedule (minimum)	150°C/1 Hour - 120°C/15 Minutes
Specific Gravity:	--- Part A: 3.71 Part B: 4.09
Pot Life:	4 Hours
Shelf Life:	One year at room temperature

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 Hour*

* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
*Color (before cure):	Part A: Silver Part B: Silver	Weight Loss:	
*Consistency:	Smooth thixotropic paste	@ 200°C:	0.06 %
*Viscosity (23°C):		@ 250°C:	0.10 %
@ 5 rpm	24,000 - 46,000 cPs	@ 300°C:	0.22 %
Thixotropic Index:	5.3	Operating Temp:	
*Glass Transition Temp:	≥ 50 °C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	Continuous:	- 55°C to + 225°C
Coefficient of Thermal Expansion (CTE):		Intermittent:	- 55°C to + 325°C
Below Tg:	37 x 10 ⁻⁶ in/in°C	Storage Modulus @ 23°C:	493,537 psi
Above Tg:	219 x 10 ⁻⁶ in/in°C	Ion Content:	
Shore D Hardness:	72	Cl ⁻ :	295 ppm
Lap Shear @ 23°C:	1,312 psi	NH ₄ ⁺ :	29 ppm
Die Shear @ 23°C:	≥ 5 Kg / 1,700 psi	Na ⁺ :	18 ppm
Degradation Temp:	402 °C	K ⁺ :	2 ppm
		*Particle Size:	≤ 45 microns

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	1.84 W/mK	Dielectric Constant (1KHz):	N/A
*Volume Resistivity @ 23°C:	≤ 0.0005 Ohm-cm	Dissipation Factor (1KHz):	N/A

OPTICAL PROPERTIES @ 23°C:			
Spectral Transmission:	N/A	Index of Refraction:	N/A

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